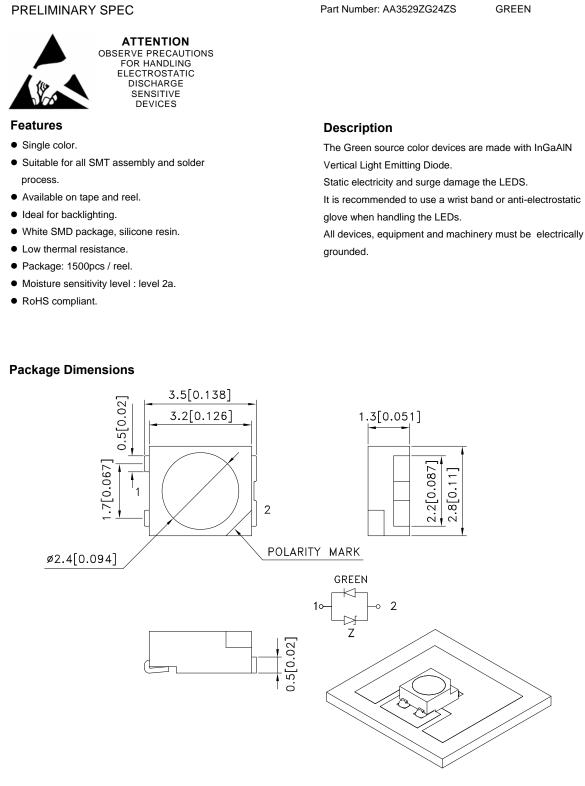
3.5x2.8 mm SMD CHIP LED LAMP



Notes:

1. All dimensions are in millimeters (inches)

2. Tolerance is ±0.25(0.01") unless otherwise noted.

Specifications are subject to change without notice.
The device has a single mounting surface. The device must be mounted according to the specifications.

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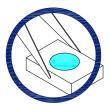
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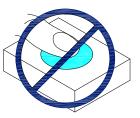
Handling Precautions

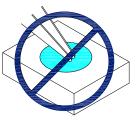
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



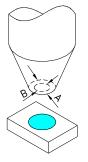


Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.

6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



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Selection Guide										
Part No.	Dice	Lens Type	lv (mcd) [2] @ 150mA		Φν (mlm) [2] @ 150mA		Viewing Angle [1]			
			Min.	Тур.	Min.	Тур.	2 θ 1/2			
AA3529ZG24ZS	GREEN (InGaAIN)	WATER CLEAR	6700	7500	18000	21000	120 °			

Notes:

1.0 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2.Luminous Intensity/ Luminous Flux: +/-15%

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	Pt	585	mW	
Junction Temperature [1]	TJ	110	°C	
Operating Temperature	Тор	-40 To +85	°C	
Storage Temperature	Tstg	-40 To +85	°C	
DC Forward Current [1]	lF	150	mA	
Peak Forward Current [2]	Іғм	350	mA	
Thermal Resistance [1] (Junction/ambient)	Rth j-a	170	°C/W	
Thermal Resistance [1] (Junction/solder point)	Rth j-S	50	°C/W	
Electrostatic Discharge Threshold (HBM)	8000	V		

Notes:

1.Results from mounting on PC board FR4(pad size ≥ 70mm²), mounted on pc board-metal core PCB is recommend

for lowest thermal Resistance.

2.1/10 Duty Cycle, 0.1ms Pulse Width.

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Value	Unit
Wavelength at peak emission IF=150mA [Typ.]	λ peak	515	nm
Dominant Wavelength IF=150mA [Typ.]	λ dom [1]	525	nm
Spectral Line Half-width IF=150mA [Typ.]	Δλ	30	nm
Forward Voltage IF=150mA [Min.]		2.9	V
Forward Voltage IF=150mA [Typ.]	VF [2]	3.4	
Forward Voltage I⊧=150mA [Max.]		3.9	
Temperature coefficient of λ peak IF=150mA, -10 ° C \leq T \leq 100 ° C [Typ.]	TC λ peak	0.09	nm/° C
Temperature coefficient of λ dom IF=150mA, -10 ° C≤T≤100 ° C [Typ.]	TC λ dom	0.03	nm/° C
Temperature coefficient of VF IF=150mA, -10 $^\circ$ C \leq T \leq 100 $^\circ$ C [Typ.]	TCv	-2.7	mV/° C

Notes

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

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